

# PS2915-1

R08DS0112EJ0201

Rev.2.01

HIGH CTR, AC INPUT RESPONSE TYPE 4-PIN ULTRA SMALL FLAT-LEAD PHOTOCOUPLER

Sep 27, 2019

## DESCRIPTION

The PS2915-1 is an optically coupled isolator containing GaAs light emitting diodes and an NPN silicon phototransistor in one package for high density mounting applications.

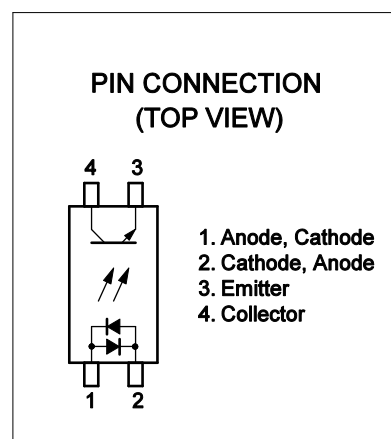
An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30%, compared with the PS28xx series.

## FEATURES

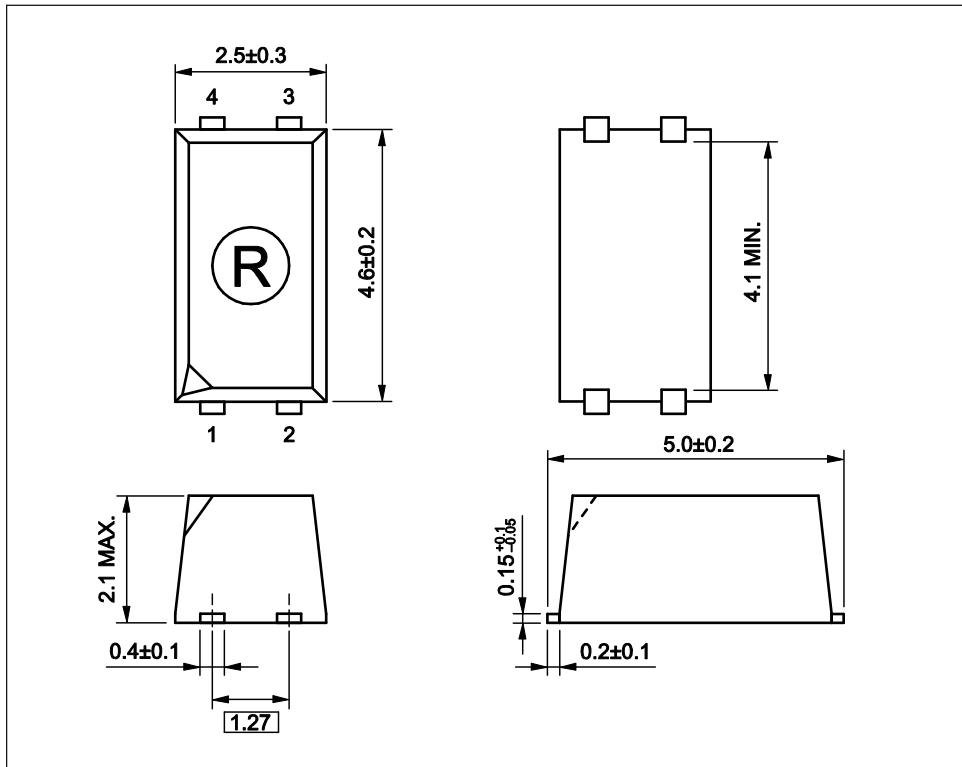
- Ultra small flat-lead package (4.6 (L) × 2.5 (W) × 2.1 (H) mm)
- High current transfer ratio (CTR = 200% TYP. @  $I_F = \pm 1$  mA,  $V_{CE} = 5$  V)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Ordering number of taping product: PS2915-1-F3, 3 500 pcs/reel
- Safety standards
  - UL approved: UL1577, Single protection
  - BSI approved: BS EN 62368-1, Supplementary insulation
  - VDE approved: DIN EN 60747-5-5 (Option)

## APPLICATIONS

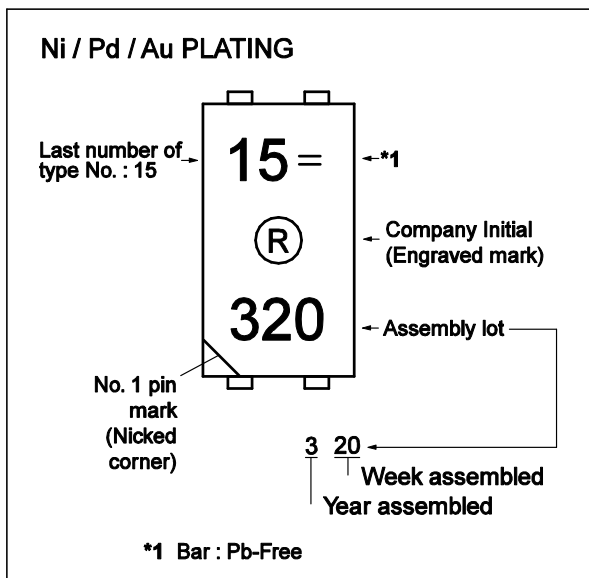
- DC/DC converter
- Modem/PC card



## PACKAGE DIMENSIONS (UNIT: mm)



## MARKING EXAMPLE



## PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.4 mm

## ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS2915-1	PS2915-1-AX	Pb-Free (Ni/Pd/Au)	50 pcs (Tape 50 pcs cut)	Standard products (UL, BSI approved)	PS2915-1
PS2915-1-F3	PS2915-1-F3-AX		Embossed Tape 3 500 pcs/reel		
PS2915-1-V	PS2915-1-V-AX		50 pcs (Tape 50 pcs cut)	UL, BSI, DIN EN 60747-5-5 approved	
PS2915-1-V-F3	PS2915-1-V-F3-AX		Embossed Tape 3 500 pcs/reel		

Note: <sup>\*1</sup>. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	$I_F$	$\pm 50$	mA
	Forward Current Derating	$\Delta I_F/^\circ\text{C}$	0.5	mA/ $^\circ\text{C}$
	Peak Forward Current <sup>*1</sup>	$I_{FP}$	$\pm 0.5$	A
	Power Dissipation	$P_D$	60	mW
Transistor	Collector to Emitter Voltage	$V_{CEO}$	40	V
	Emitter to Collector Voltage	$V_{ECO}$	5	V
	Collector Current	$I_C$	40	mA
	Power Dissipation Derating	$\Delta P_C/^\circ\text{C}$	1.2	mW/ $^\circ\text{C}$
	Power Dissipation	$P_C$	120	mW
Isolation Voltage <sup>*2</sup>		$BV$	2 500	Vr.m.s.
Total Power Dissipation		$P_T$	160	mW
Operating Ambient Temperature		$T_A$	-55 to +100	$^\circ\text{C}$
Storage Temperature		$T_{stg}$	-55 to +150	$^\circ\text{C}$

Notes: <sup>\*1</sup>.  $PW = 100 \mu\text{s}$ , Duty Cycle = 1%

<sup>\*2</sup>. AC voltage for 1 minute at  $T_A = 25^\circ\text{C}$ , RH = 60% between input and output  
Pins 1-2 shorted together, 3-4 shorted together.

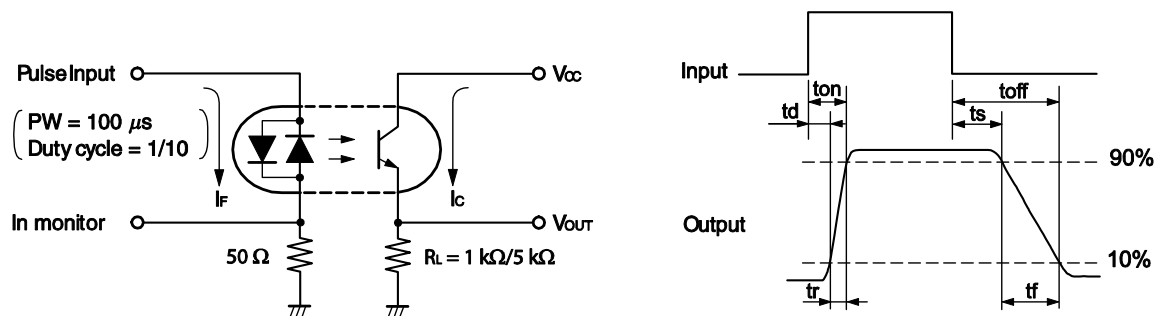
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)**

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = ±1 mA	0.9	1.1	1.3	V
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1 MHz		30		pF
Transistor	Collector to Emitter Dark Current	I <sub>CEO</sub>	I <sub>F</sub> = 0 mA, V <sub>CE</sub> = 40 V			100	nA
Coupled	Current Transfer Ratio (I <sub>C</sub> /I <sub>F</sub> )* <sup>1</sup>	CTR	I <sub>F</sub> = ±1 mA, V <sub>CE</sub> = 5 V	100	200	400	%
	Collector Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>F</sub> = ±1 mA, I <sub>C</sub> = 0.2 mA		0.13	0.3	V
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kVDC	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time* <sup>2</sup>	t <sub>r</sub>	V <sub>CC</sub> = 5 V, I <sub>C</sub> = 2 mA, R <sub>L</sub> = 1 kΩ		5		μs
	Fall Time* <sup>2</sup>	t <sub>f</sub>			10		
	Turn-on Time* <sup>2</sup>	t <sub>on</sub>	V <sub>CC</sub> = 5 V, I <sub>F</sub> = ±1 mA, R <sub>L</sub> = 5 kΩ		40		μs
	Storage Time* <sup>2</sup>	t <sub>s</sub>			10		μs
	Turn-off Time* <sup>2</sup>	t <sub>off</sub>			120		μs

Notes: \*1 CTR rank

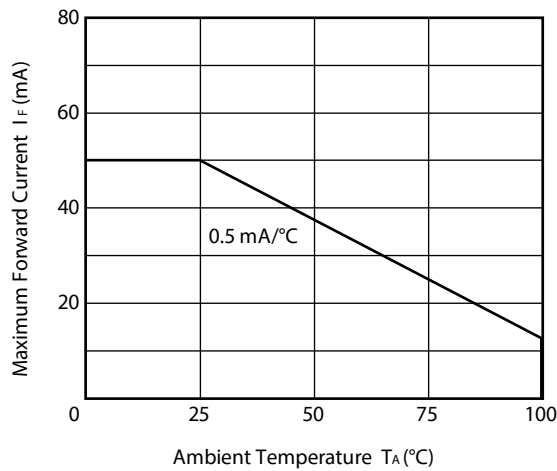
N : 100 to 400 (%)

\*2 Test circuit for switching time

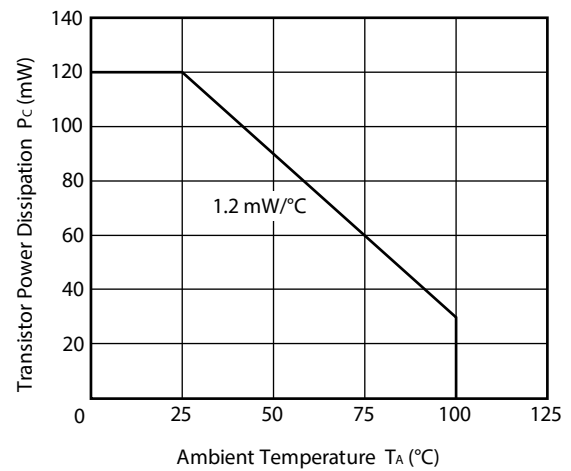


# TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

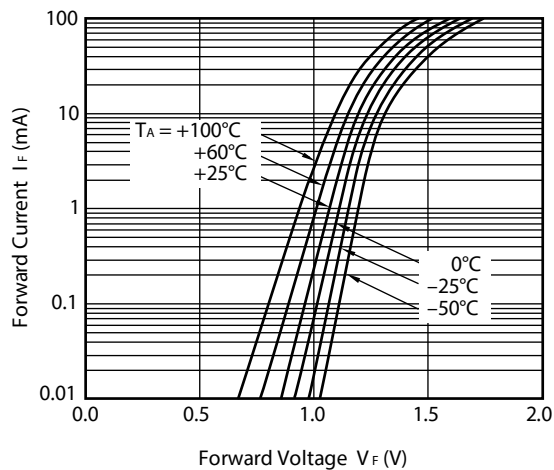
MAXIMUM FORWARD CURRENT vs.  
AMBIENT TEMPERATURE



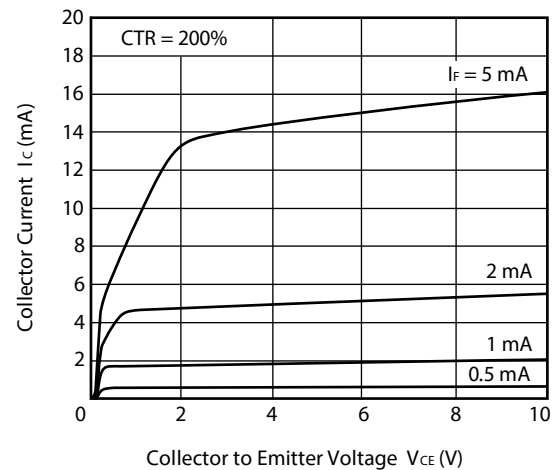
TRANSISTOR POWER DISSIPATION  
vs. AMBIENT TEMPERATURE



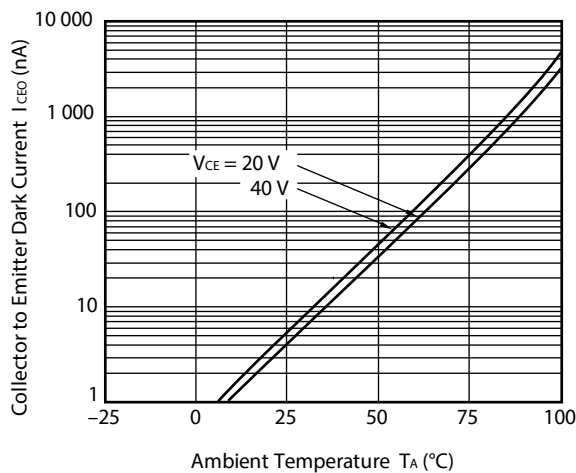
FORWARD CURRENT vs.  
FORWARD VOLTAGE



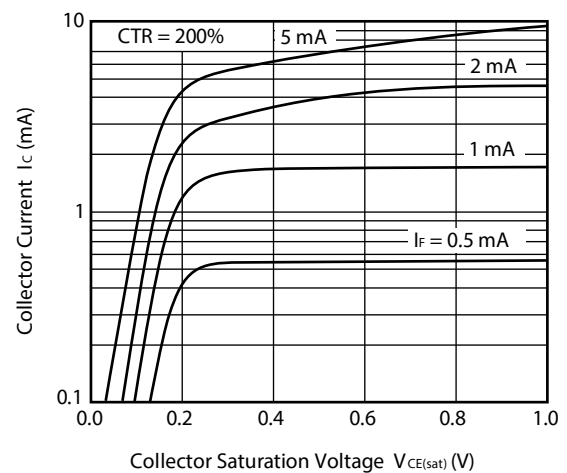
COLLECTOR CURRENT vs.  
COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK  
CURRENT vs. AMBIENT TEMPERATURE

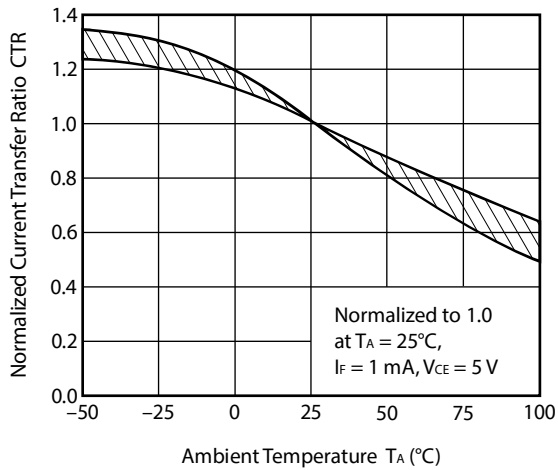


COLLECTOR CURRENT vs.  
COLLECTOR SATURATION VOLTAGE

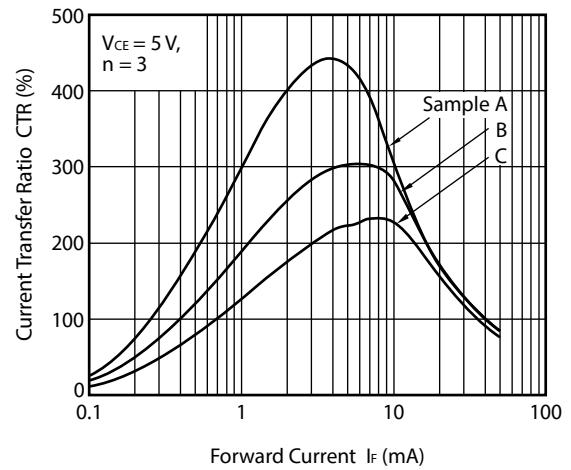


**Remark** The graphs indicate nominal characteristics.

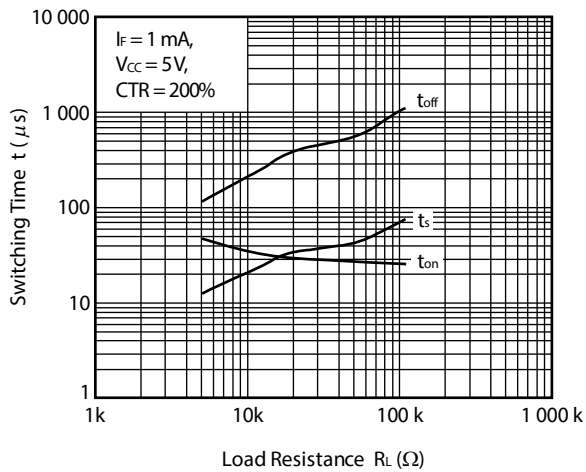
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



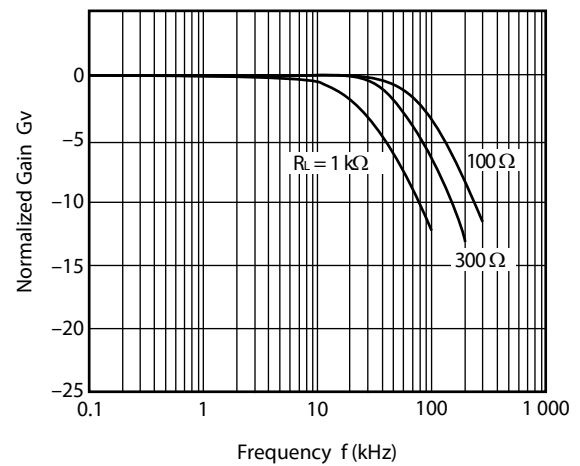
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



SWITCHING TIME vs. LOAD RESISTANCE



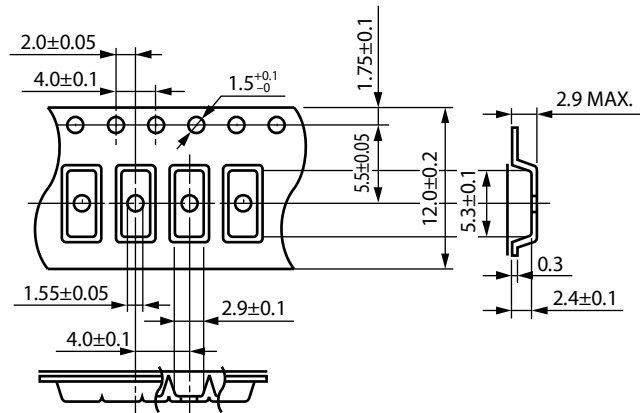
FREQUENCY RESPONSE



**Remark** The graphs indicate nominal characteristics.

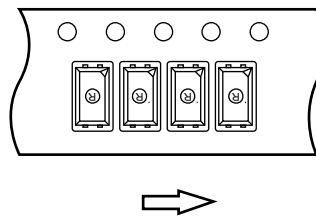
## TAPING SPECIFICATIONS (UNIT: mm)

## Outline and Dimensions (Tape)

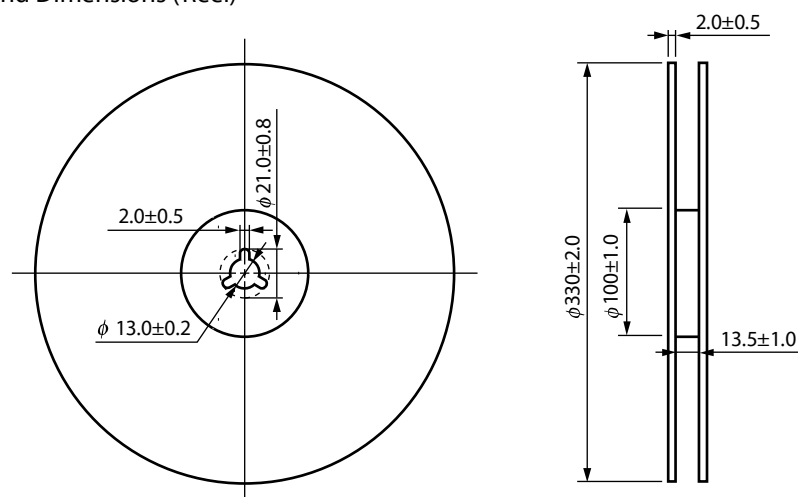


## Tape Direction

PS2915-1-F3

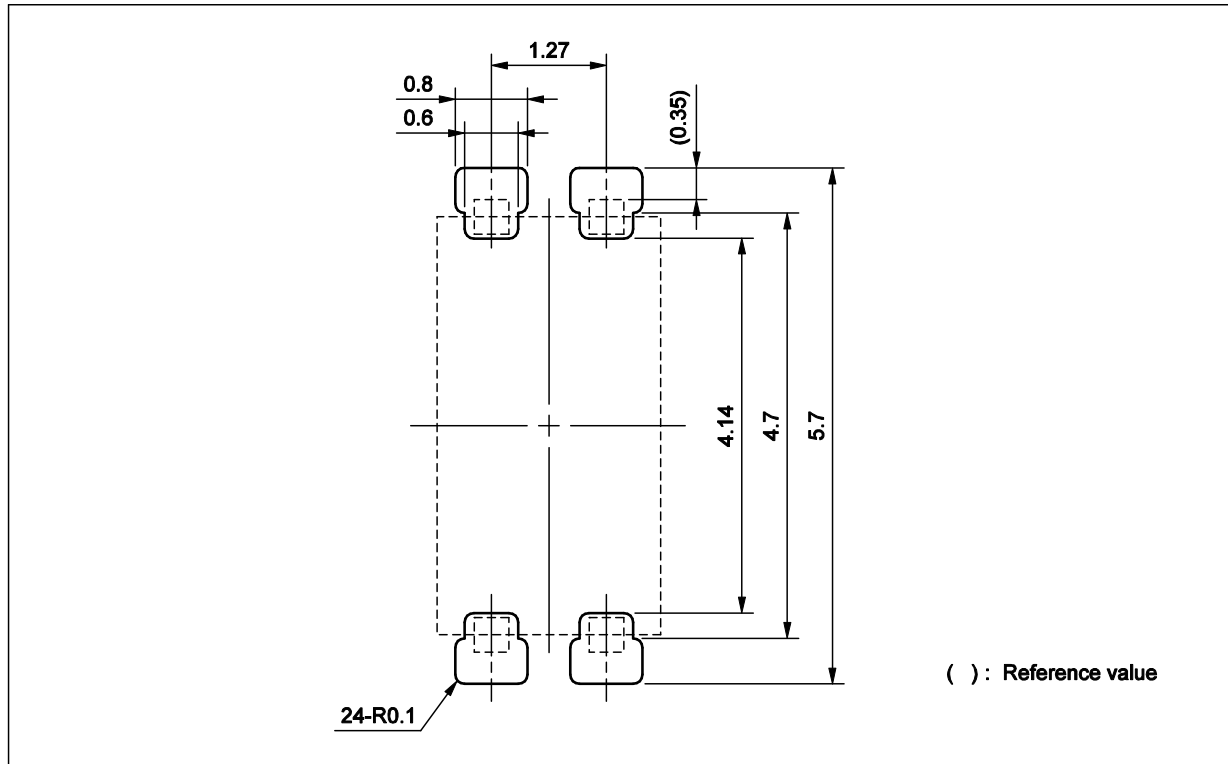


## Outline and Dimensions (Reel)



Packing: 3 500 pcs/reel

## RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.



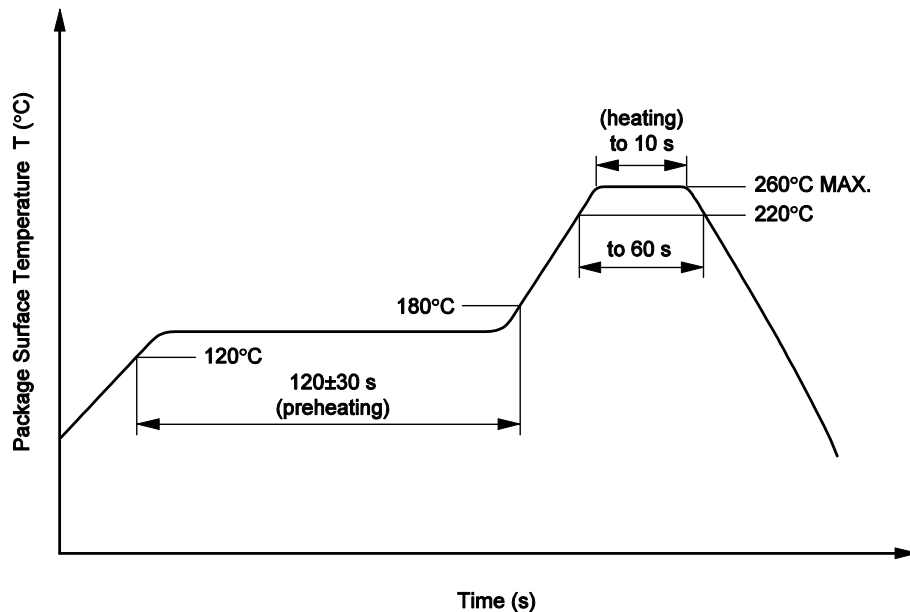
## NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- |   |  |
|---|--|
| • Peak reflow temperature                       | 260°C or below (package surface temperature)   |
| • Time of peak reflow temperature               | 10 seconds or less   |
| • Time of temperature higher than 220°C         | 60 seconds or less   |
| • Time to preheat temperature from 120 to 180°C | 120 ± 30 s   |
| • Number of reflows                             | Three  |
| • Flux  | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

**Recommended Temperature Profile of Infrared Reflow**



#### (2) Wave soldering

- |                         |  |
|-------------------------|--|
| • Temperature           | 260°C or below (molten solder temperature)   |
| • Time                  | 10 seconds or less   |
| • Preheating conditions | 120°C or below (package surface temperature)   |
| • Number of times       | One (Allowed to be dipped in solder including plastic mold portion.)   |
| • Flux                  | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

#### (3) Soldering by Soldering Iron

- |  |  |
|--|--|
| • Peak Temperature (lead part temperature) | 350°C or below   |
| • Time (each pins)                         | 3 seconds or less  |
| • Flux                                     | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.) |

Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

#### (4) Cautions

- Flux Cleaning  
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.

**2. Cautions regarding noise**

Be aware that when voltage is applied suddenly between the photocoupler's input and output at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

**3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler**

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

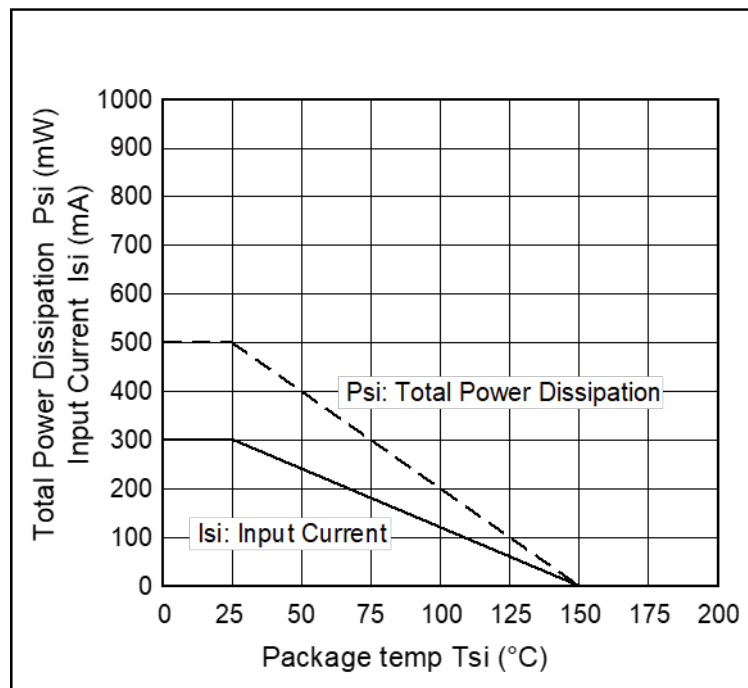
**USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

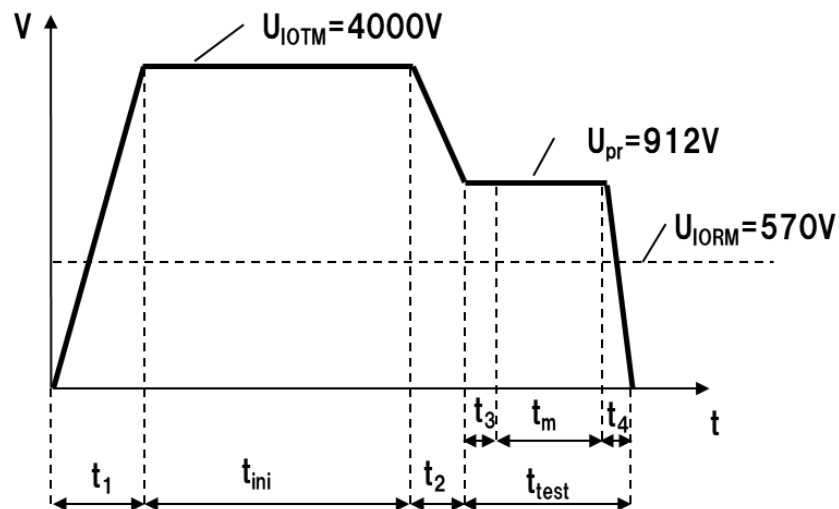
## SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength			
maximum operating isolation voltage	$U_{IORM}$	570	$V_{peak}$
Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.6 \times U_{IORM.}, P_d < 5 \text{ pC}$	$U_{pr}$	912	$V_{peak}$
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM.}, P_d < 5 \text{ pC}$	$U_{pr}$	1068	$V_{peak}$
Highest permissible overvoltage	$U_{TR}$	4 000	$V_{peak}$
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	$T_{stg}$	-55 to +150	°C
Operating temperature range	$T_A$	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc at } T_A = 25^\circ\text{C}$	$R_{is \text{ MIN.}}$	$10^{12}$	$\Omega$
$V_{IO} = 500 \text{ V dc at } T_A \text{ MAX. at least } 100^\circ\text{C}$	$R_{is \text{ MIN.}}$	$10^{11}$	$\Omega$
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)			
Package temperature	$T_{si}$	150	°C
Current (input current $I_F$ , $\Psi_i = 0$ )	$I_{si}$	300	mA
Power (output or total power dissipation)	$\Psi_i$	500	mW
Isolation resistance $V_{IO} = 500 \text{ V dc at } T_A = T_{si}$	$R_{is \text{ MIN.}}$	$10^9$	$\Omega$

## Dependence of maximum safety ratings with package temperature



### Method a) Destructive Test, Type and Sample Test



$t_1, t_2 = 1$  to  $10$  sec

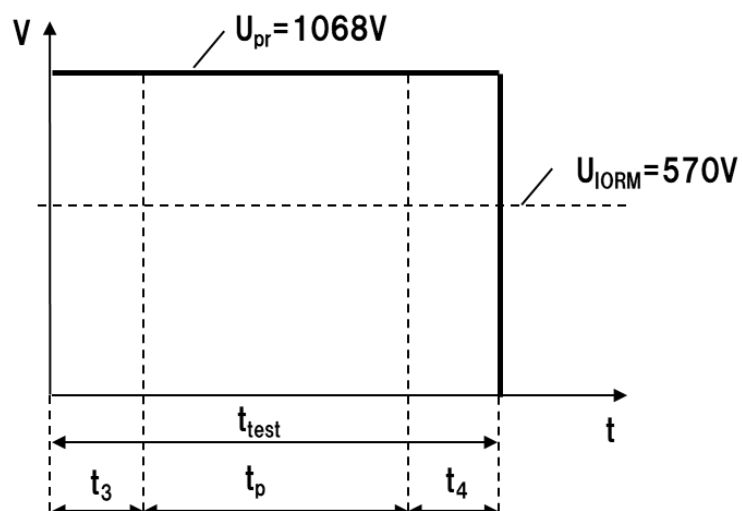
$t_3, t_4 = 1$  sec

$t_m$  (PARTIAL DISCHARGE) =  $10$  sec

$t_{test} = 12$  sec

$t_{ini} = 60$  sec

### Method b) Non-destructive Test, 100% Production Test



$t_3, t_4 = 0.1$  sec

$t_p$  (PARTIAL DISCHARGE) =  $1.0$  sec

$t_{test} = 1.2$  sec

<b>Caution</b>	<p>GaAs Products</p>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"><li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.</li><li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li><li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li><li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li><li>• Do not lick the product or in any way allow it to enter the mouth.</li></ul>
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**Renesas Electronics Corporation**  
TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan

**Renesas Electronics America Inc.**  
1001 Murphy Ranch Road, Milpitas, CA 95035, U.S.A.  
Tel: +1-408-432-8888, Fax: +1-408-434-5351

**Renesas Electronics Canada Limited**  
9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3  
Tel: +1-905-237-2004

**Renesas Electronics Europe GmbH**  
Arcadiastrasse 10, 40472 Düsseldorf, Germany  
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

**Renesas Electronics (China) Co., Ltd.**  
Room 101-T01, Floor 1, Building 7, Yard No. 7, 8th Street, Shangdi, Haidian District, Beijing 100085, China  
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

**Renesas Electronics (Shanghai) Co., Ltd.**  
Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai 200333, China  
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

**Renesas Electronics Hong Kong Limited**  
Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong  
Tel: +852-2265-6688, Fax: +852 2886-9022

**Renesas Electronics Taiwan Co., Ltd.**  
13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan  
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

**Renesas Electronics Singapore Pte. Ltd.**  
80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949  
Tel: +65-6213-0200, Fax: +65-6213-0300

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Unit No 3A-1 Level 3A Tower 8 UOA Business Park, No 1 Jalan Pengaturcara U1/51A, Seksyen U1, 40150 Shah Alam, Selangor, Malaysia  
Tel: +60-3-5022-1288, Fax: +60-3-5022-1290

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No.777C, 100 Feet Road, HAL 2nd Stage, Indiranagar, Bangalore 560 038, India  
Tel: +91-80-67208700

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17F, KAMCO Yangjae Tower, 262, Gangnam-daero, Gangnam-gu, Seoul, 06265 Korea  
Tel: +82-2-558-3737, Fax: +82-2-558-5338